



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-06-05
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Rossana Bonaccorso
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	I9Z7*U726BAZ	A	0959	2018-06-05
Amount	UoM	Unit type	ST ECOPACK Grade	
500	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	3.9-4.9-1.25	20	GULL WING	
Comment	Package: SO 20 .30 TO JEDEC MS-013 - MDF valid for CPs: L9997ND013TR and L9997ND			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	TRUE		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	FALSE		
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	I927*U726BAZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	5.994	mg	supplier	die	Silicon (Si)	7440-21-3		5.815	mg	970137	11630
				supplier	metallization	Aluminium (Al)	7429-90-5		0.033	mg	5506	66
				supplier	metallization	Copper (Cu)	7440-50-8		0.001	mg	166	2
				supplier	Passivation	Silicon Nitride	12033-89-5		0.019	mg	3170	38
				supplier	Passivation	Silicon Oxide	7631-86-9		0.078	mg	13013	156
Leadframe	M-004 Copper and its alloys	172.380	mg	supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.048	mg	8008	96
				supplier	alloy	Copper (Cu)	7440-50-8		171.920	mg	997331	343840
				supplier	alloy	Iron (Fe)	7439-89-6		0.172	mg	998	344
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.052	mg	302	104
				supplier	metallization	Silver (Ag)	7440-22-4		0.236	mg	1369	472
Die attach	M-015 Other organic materials	1.419	mg	supplier	glue	Silver (Ag)	7440-22-4		1.213	mg	854827	2426
				supplier	glue	Dodecyl acrylate	2156-97-0		0.036	mg	25371	72
				supplier	glue	methylene diacrylate	42594-17-2		0.114	mg	80338	228
				supplier	glue	Diglycidylphenyl glycidyl ether	13561-08-5		0.028	mg	19732	56
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.014	mg	9866	28
Bonding wires	M-011 Other inorganic materials	0.299	mg	supplier	glue	dimethylbenzyl peroxide	80-43-3		0.014	mg	9866	28
				supplier	wire	Copper (Cu)	7440-50-8		0.299	mg	1000000	598
Encapsulation	M-011 Other inorganic materials	317.336	mg	supplier	mold compound	Silica, vitreous	60676-86-0		274.495	mg	864998	548990
				supplier	mold compound	Epoxy resin	25068-38-6		31.734	mg	100001	63468
				supplier	mold compound	Phenol resin	29690-82-2		9.520	mg	30000	19040
Connections coating	Solder	2.572	mg	supplier	mold compound	Carbon black	1333-86-4		1.587	mg	5001	3174
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.572	mg	1000000	5144